



3rd INTERNATIONAL EOS/ESD SYMPOSIUM ON DESIGN AND SYSTEM (IEDS)

May 8-10, 2024

Hangzhou, China

ORGANIZING COMMITTEE

Conference Advisory Chair

Hanming Wu, Zhejiang University

Ming-Dou Ker, National Yang Ming Chiao Tung University

Conference Chair Emeritus

Junjun Li, ESDA

Shurong Dong, Zhejiang University

Conference Chair

Rui Zhang, Zhejiang University

Conference Co-Chair

Shih-Hung Chen, IMEC

Technical Program Chair

Chun-Yu Lin, National Taiwan Normal University

Technical Program Co-Chair

Jie Zeng, GLOBALFOUNDRIES

Workshop Chair

Guangyi Lu, HiSilicon

Local Arrangement Chair

Qiang Cui, Zhejiang University

Publicity Chair(s)

Bernard Chin, Qorvo

Xiaozong Huang, CETC-24

Xiangliang Jin, Hunan Normal University

Huijuan Wang, Honor

Yafei Yuan, BOIMT

Sen Zhang, CSMC

Yulong Zhu, Hanwa

Conference Event Manager

Christina Earl, ESDA Business Operations Manager

Conference Technical Advisor

Nathaniel Peachey, Qorvo, ESDA Senior Vice President

Conference Program Advisor

Lisa Pimpinella, ESDA Executive Director

CALL FOR PAPERS

EOS/ESD Association, Inc. is sponsoring the 3rd International EOS/ESD Symposium on Design and System (IEDS). IEDS 2024 is dedicated to the fundamental understanding of issues related to electrostatic discharge on design and system and the application of this knowledge to the solution of problems. The Technical Program Committee solicits symposium contributions, including data and analysis that advance the state-of-the-art knowledge, enhance or review the general knowledge, or discuss new topics related to on-chip ESD design, system ESD design, and EOS/ESD issues in manufacturing. The Technical Program Committee is inviting papers related, but not limited, to the following tracks:

- ✓ Advanced CMOS EOS/ESD and Latch-up
- ✓ ESD protection in Bipolar, RF, High-voltage, and BCD technologies
- ✓ ESD modeling, simulation and design automation
- ✓ EOS/ESD Failure analysis and case studies
- ✓ ESD and Latch-up testing
- ✓ System ESD design and troubleshooting issues
- ✓ ESD manufacturing control issues and target discussion
- ✓ Device, circuit and product reliability

Event Highlights: Awards are presented annually for the Symposium Outstanding Paper and Best Student Paper Award (selected by the Technical Program Committee). The Outstanding Paper is considered for presentation at the Annual EOS/ESD Symposium.

IMPORTANT DATES

October 16, 2023

Abstract Paper Submission Deadline

November 16, 2023

Notification of Acceptance

January 12, 2024

Author Registration/Final Paper

Submission Deadline

Submission Guidelines

Authors must submit a maximum 50-word abstract and maximum 4-page summary of their work. The summary must clearly state the purpose, results (e.g., data, diagrams, photographs, etc.), and conclusions of the work. Summaries must also include references to prior publications and state how the work enhances existing knowledge. Authors suggest the technical area related to their submission. Abstract submissions can be made electronically at: <https://softconf.com/n/eos-esd2024>